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**RESPONSE UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE - EXAMINING GROUP 2800**

**PATENT**

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to Box AF, Commissioner of Patents, Washington, DC 20231.

December 10, 2002 Stephanie Jansen  
Date Stephanie Jansen

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants : Salman Akram; Alan G. Wood;  
Warren M. Farnworth

Attorney Docket No.: 500185.03

Serial No. : 09/631,900

Group Art Unit : 2827

Filed : August 4, 2000

Examiner : Lourdes C. Cruz

Title : APPARATUS AND METHODS OF TESTING AND ASSEMBLING BUMPED  
DEVICES USING AN ANISOTROPICALLY CONDUCTIVE LAYER

Box AF  
Commissioner of Patents  
Washington, DC 20231

**RESPONSE UNDER 37 C.F.R. § 1.116**

Sir:

Applicants acknowledge receipt of the Office Action dated September 10, 2002.

**In the Claims:**

Please cancel claims 15-17 and amend claims 1 and 9 as follows:

1. (Twice Amended) A semiconductor device, comprising:  
a bumped device having a plurality of conductive bumps formed thereon;

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